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(71) Applicant: **MERCK PATENT GMBH** [DE/DE]; Frankfurter Strasse 250, 64293 Darmstadt (DE).

(72) Inventors: **MEYER, Frank**; Hoehenblick 7a, 61479 GLASHUETTEN (DE). **LARBIG, Gregor**; Hauptstrasse 3, 63571 GELNHAUSEN (DE). **KOPPE, Karsten**; Borsdorffstrasse 2a, 64289 DARMSTADT (DE).

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(54) Title: DIELECTRIC MATERIALS

(57) Abstract: The present invention relates to a novel class of polymers which can be used as dielectric material for the preparation of passivation layers in electronic devices. The polymers are prepared from polymerizable compounds having mesogenic groups and they provide excellent film forming capability and excellent mechanical properties and have a low dielectric constant and a low coefficient of thermal expansion (CTE). There is further provided a method for forming said polymers and an electronic device containing said polymers as dielectric material. Beyond that, the present invention relates to a manufacturing method for preparing a packaged microelectronic structure and to a microelectronic device comprising said packaged microelectronic structure formed by said manufacturing method.



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